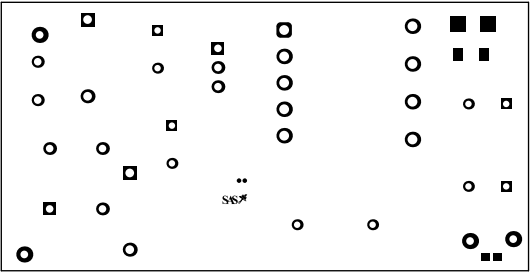
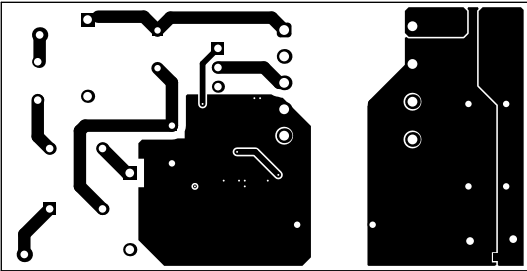


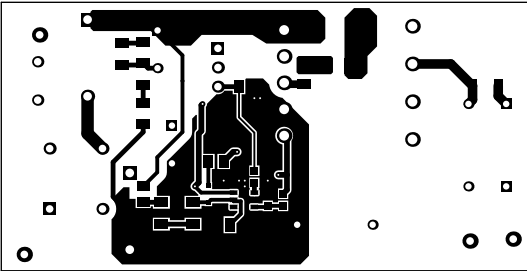
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20990	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 12/1/2017 11:50:14 AM	TEXAS INSTRUMENTS	



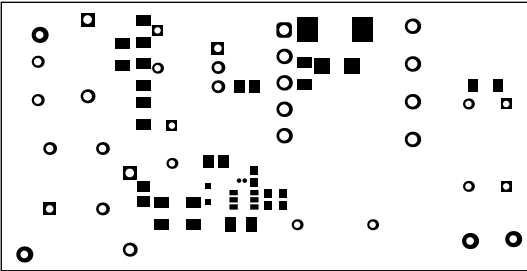
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20990	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 12/1/2017 11:50:16 AM		TEXAS INSTRUMENTS



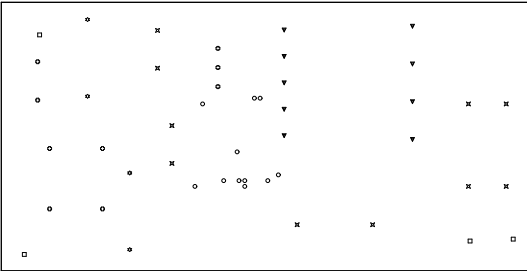
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20990	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 12/1/2017 11:50:17 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20990	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 12/1/2017 11:50:18 AM		TEXAS INSTRUMENTS

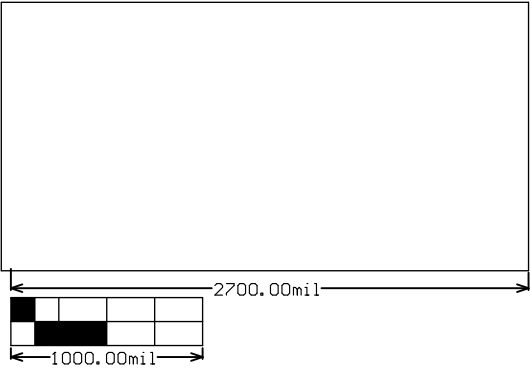


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20990	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/1/2017 11:50:20 AM		TEXAS INSTRUMENTS



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair
○	11	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer
⊗	10	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer
⊕	9	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer
□	4	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer
☆	4	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer
▼	9	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer
	47 Total				

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20990	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 12/1/2017 11:50:24 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PMP20990	REV:	A	SUN REV:	Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:	N/A				
PLOT NAME = Board Dimensions	GENERATED	: 12/1/2017	11:50:26 AM	TEXAS INSTRUMENTS		

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